

# MECHANICAL CASE OUTLINE

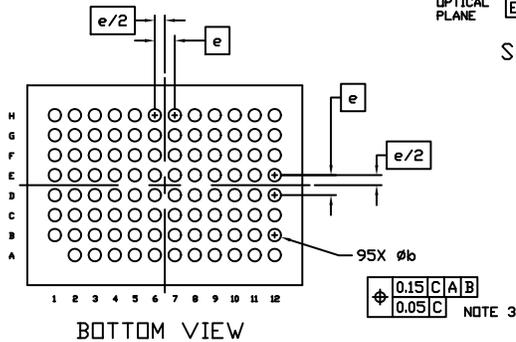
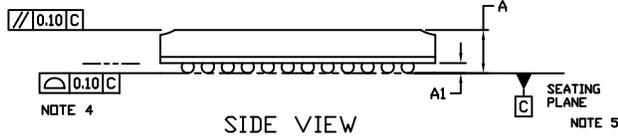
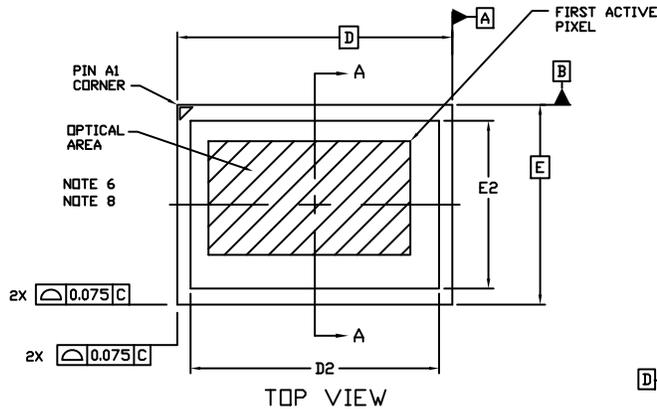
## PACKAGE DIMENSIONS

ON Semiconductor®

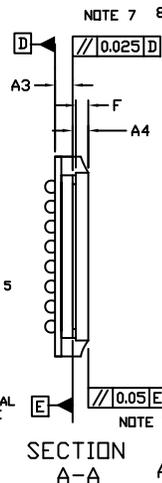


IBGA95 11x8  
CASE 503BW  
ISSUE O

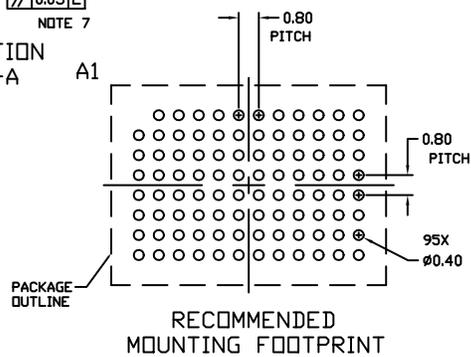
DATE 16 OCT 2017



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
  4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
  5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
  6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE 1°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
  7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
  8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=-213.545 MICRONS, Y=265.14 MICRONS ±75 MICRONS.



DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.88
A1	0.35	0.45
A3	0.65	0.75
A4	0.575	0.675
b	0.45	0.55
D	11.00 BSC	
D2	9.85	10.05
E	8.00 BSC	
E2	6.62	6.82
e	0.80 BSC	
F	0.45	0.55



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